

1703 E. Highway 50 Yankton, SD 57078 USA

Phone: 800-762-8800 or 605-665-9321 Fax: 605-665-1709

Website: www.mtronpti.com



SPECIFICATION FOR 3.2 mm x 5.0 mm SMT TCXO MtronPTI P/N M6053S001

Electrical Specifications:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency	Fo		26.000000		MHz	
Frequency Tolerance	F/F	-1.0 -2.5 -0.2 -0.3		+1.0 +2.5 +0.2 +0.3	ppm ppm ppm ppm	@ +25 °C, initial
Frequency Stability	ΔF/F					Over Operating Temperature, ref. to +25 °C For ±5% Voltage Change For ±5% Load Change
Frequency vs. Supply						
Frequency vs. Load	F∟					
Frequency vs. Aging		-1		+1	ppm	Per year @ 40 °C
Overall Frequency Stability		-10.0		+10.0	ppm	Including frequency tolerance at +25 °C, deviation over operating temperature range, reflow soldering, supply voltage change, output load change, and aging for 10 years.
Operating Temperature	TA	-40		+85	°C	
Operating Voltage	V_{DD}	2.850	3.000	3.150	V	
Operating Current	I _{DD}			2.0	mA	
Output Type		Cli	pped Sine Wa	ive		
Output Load			10 kΩ 10 pF			
Output Level		0.8			V pk-pk	
Phase Noise			-85 -110 -135 -150		dBc/Hz dBc/Hz dBc/Hz dBc/Hz	@ 10 Hz @ 100 Hz @ 1 kHz @ 10 kHz

Environmental Conditions:

Mechanical Shock	Per MIL-STD-202, Method 213, (2000 g's, 0.3 ms duration, ½ sine wave)
Vibration	Per MIL-STD-202, Method 201 & 204 (10 g's from 20 Hz - 2000 Hz)
Hermeticity	Per MIL-STD-202, Method 112 (1 x 10 ⁻⁸ atm cc/s of Helium) (crystal unit only)
Storage Temperature	-55 °C to +105 °C
Solderability	Per EIAJ-STD-002
Max. Soldering Conditions	See solder profile, Figure 1
Package	4-pad 3.2 mm x 5.0 mm x 1.5 mm leadless ceramic. RoHS compliant.



...when timing matters

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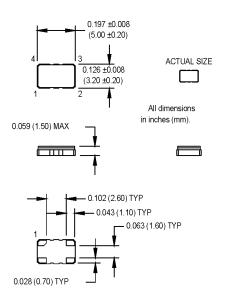
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Dimensions, Marking, and Pin Out Information

P	Part Marking	
Line 1	xxMxxx	
Line 2	Mywv	

	Legend
xxMxxx	Frequency in MHz
у	Year
w	Work Week
V	Factory Code

Pad	Function	
1	No Connection	
2	GND	
3	Output	
4	+V _{DD}	



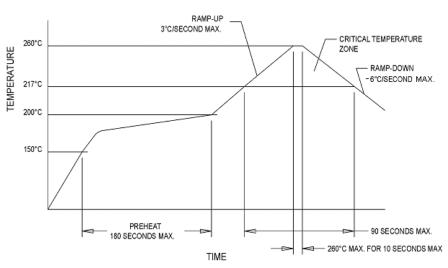
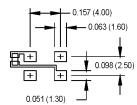


Figure 1

SUGGESTED SOLDER PAD LAYOUT



Data Sheet Revision Table:

Date	Rev.	Author	Details of Revision
11/06/12	0	LEO	Original release.